CK.0000071713

Electrical Modeling and Design for 3D System Integration

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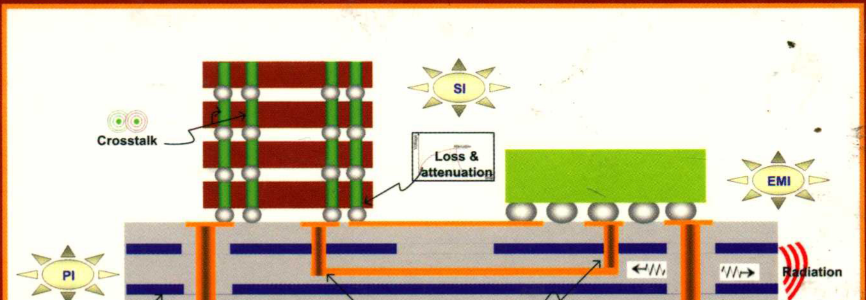
Power Integrity and EMC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Library of Congress Cataloging-in-Publication Data:

Li, Er-Ping.
Electrical modeling and design for 3D system integration : 3D integrated circuits and packaging, signal integrity, power integrity and EMC / Er-Ping Li.
p. cm.
ISBN 978-0-470-62346-6 (hardback)
1. Three-dimensional integrated circuits. I. Title.
TK7874.893.L53 2011
621.3815–dc23

2011028946

Printed in the United States of America.

10 9 8 7 6 5 4 3 2 1

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